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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

More application of:

Chii-Ming WU, et al.

Serial No.: 10/657,505

Filed: September 8, 2003

For: Method of Manufacturing a Contact Interconnection Layer Containing a Metal and Nitrogen by Atomic Layer Deposition for Deep Sub-Micron Semiconductor Technology

§ 87(2)(b)

Confirmation No. 9336

Group Art Unit: 2812

Examiner: Jennifer M. Kennedy

Commissioner for Patents  
Mail Stop Amendment  
P.O. Box 1450  
Alexandria, VA 22313-1450

## AMENDMENT

Sir:

No fees, including extension of time fees, are believed necessary for consideration of the present paper. However, if any fees, including extension of time fees, are necessary, the extension of time is hereby requested, and the Commissioner is hereby authorized to charge any fees, including those for the extension of time, to Haynes and Boone, LLP's Deposit Account No. 08-1394.

In response to the Office action of October 26, 2005, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on **page 2** of this paper.

**Remarks begin on page 14 of this paper.**